Point Soldering Unit Operational Sequence sheet

1. Preparing to solder. Heater opens.
   - Solder cup
   - Cutter
   - Solder chip
   - Guide (cradle block)
   - Solder chip sensor
   - Ceramic heater
   - Circuit board
   - Lead

2. Initial lowering of heater and guide.
   - Rotating solder cup in c.c.w.
   - Guide down.
   - Heater opens.

3. Heater closes and solder charged.
   - Solder pieces are supplied. After confirming transit of the solder pieces, melting time starts.
   - Heater down.
   - Heater closed.
   - Solder chip melts.

4. Solder melts and guide up.
   - After solder is supplied, guide up.
   - Melted solder goes lead and pattern.

5. The next piece of solder is cut. The heater opens and the solder chip drops.
   - Cutting solder for next point. Keeping solder chip in the cup.
   - Cutter up.
   - Heater closed.

6. After heating, heater opens and up.
   - Feeding Solder.
   - Cutter up.
   - Heating.

7. Second lowering of heater. Begins heating of the solder and pattern.
   - Cutting solder again (In case of solder is supplied few times.)
   - Heating.
   - Heating. Through hole to be wet.

8. After Solder tip drops the heater closes.
   - Feeding solder.
   - Cutter up.

9. Soldering is completed. Waiting for the next point.
   - After confirming transit of the solder pieces, melting time starts.
   - Through hole to be wet.
   - Heater opens up.

    - Soldering is completed.